

 INFORMATION DISCLOSURE CITATION (Use several sheets if necessary)	Docket Number (Optional) FIS920020007	Application Number 10/605,204
	Applicant(s) Pogge et al.	
	Filing Date 09-15-03	Group Art Unit 2827

U.S. PATENT DOCUMENTS

*EXAMINER INITIAL	REF	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE

FOREIGN PATENT DOCUMENTS

	REF	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
							YES	NO

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

AC	"Novel microelectronic packaging method for reduced thermomechanical stresses on low dielectric constant materials", Emery et al., Intel Corp.
AC	"Bridging the chip/package process divide", Pogge et al., IBM Microelectronics

EXAMINER Alonso Chambliss	DATE CONSIDERED 6/28/04
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EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP Section 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of Invention

INTEGRATED ELECTRONIC CHIP AND INTERCONNECT
DEVICE AND PROCESS FOR MAKING THE SAME

Application Number :

Confirmation Number:

First Named Applicant: H. Pogge

Attorney Docket Number: FIS920020007

Art Unit:

Examiner:

Search string: (4670770 or 4783695 or 4884122 or 4933042 or 4949148 or 5019535 or 5353498
or 5373627 or 5998868 or 6025638 or 6066513 or 6087199 or 6110806 or 6444560
or 20020020924).pn

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
AC	1	4670770	1987-06-02	Thai			
	2	4783695	1988-11-08	Eichelberger et al.			
	3	4884122	1989-11-28	Eichelberger et al.			
	4	4933042	1990-06-12	Eichelberger et al.			
	5	4949148	1990-08-14	Bartelink			
	6	5019535	1991-05-28	Wojarowski et al.			
	7	5353498	1994-10-11	Fillion et al.			
	8	5373627	1994-12-20	Grebe			
	9	5998868	1999-12-12	Pogge et al.			
	10	6025638	2000-02-15	Pogge et al.			
	11	6066513	2000-05-23	Pogge et al.			
	12	6087199	2000-07-11	Pogge et al.			
	13	6110806	2000-08-29	Pogge			
AC	14	6444560	2002-09-03	Pogge et al.			

US Published Applications

Note: Applicant is not required to submit a paper copy of cited US Published Applications

init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
AC	1	20020020924	2002-02-21	Mueller et al.			

Signature

Examiner Name	Date
<i>Atamp Chambliss</i>	6/28/04